AMENDMENTS TO THE CLAIMS

Please amend claims 1, 13, 18, and 27.

Please enter the pending claims as follows:

This listing of the claims replaces all prior versions, and listings, of claims in the application.

Listing of the Claims

1. (Currently Amended) A method comprising:

determining an index-matching liquid;

determining a set of one or more constituents based on said indexmatching liquid;

providing a photoresist;

adding said set of one or more constituents to said photoresist;

and

altering liquid-contact properties of said photoresist, said properties comprising density, wet ability, and molecular organization.

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- 2. (Previously Presented) The method of claim 1 wherein said set of one or more constituents is determined based upon said index-matching liquid of an immersion lithography exposure system.
- 3. (Previously Presented) The method of claim 2 wherein said index-matching liquid comprises water.
- 4. (Previously Presented) The method of claim 3 wherein said set of one or more constituents comprises at least one water-insoluble constituent.
- 5. (Previously Presented) The method of claim 4 wherein said at least one waterinsoluble constituent is selected from a group consisting of a hydrophobic ionic photoacid generator and a non-ionic photoacid generator.
- 6. (Previously Presented) The method of claim 4 wherein said at least one waterinsoluble constituent comprises a water-insoluble quencher.
- 7. (Previously Presented) The method of claim 4 wherein said at least one waterinsoluble constituent comprises a water-insoluble polymer.
- 8. (Previously Presented) The method of claim 4 wherein water-soluble constituents are bound to said at least one water insoluble constituent via a binding method Serial No.: 10/688.109 3 Attorney's Docket No.: 42P17302

selected from a group consisting of covalent binding, ion pairing, and Van der Waal's forces.

- (Previously Presented) The method of claim 4 wherein said at least one waterinsoluble constituent may react when said photoresist is used to modulate susceptibility to etch.
- 10. (Previously Presented) The method of claim 3 wherein said set of one or more constituents comprises at least one water-soluble constituent.
- 11. (Previously Presented) The method of claim 10 wherein said at least one water-soluble constituent is selected from a group consisting of a water-soluble photoacid generator, a water-soluble quencher, a water-soluble buffer, a water-soluble surfactant, and a water-soluble plasticizer.
- 12. (Previously Presented) The method of claim 11 wherein said water-soluble surfactant is a fluorocarbon-based surfactant.
- 13. (Currently Amended) An apparatus comprising:

 a substrate:

a photoresist deposited on said substrate, said photoresist having incorporated therein one or more additives that alter <u>improve</u> liquid-contact properties of said photoresist;

an index-matching liquid disposed in contact with said photoresist;

and

liquid.

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a last lens element disposed in contact with said index-matching

- 14. (Previously Presented) The apparatus of claim 13 wherein said liquid-contact properties of said photoresist are specific to a particular liquid.
- 15. (Previously Presented) The apparatus of claim 14 wherein said particular liquid comprises water and said one or more additives comprises at least one hydrophobic additive.
- 16. (Previously Presented) The apparatus of claim 15 wherein said at least one hydrophobic additive comprises an ionic photoacid generator.
- 17. (Previously Presented) The apparatus of claim 15 wherein said at least one hydrophobic additive comprises a water-insoluble quencher.

- 18. (Currently Amended) The apparatus of claim 15 wherein at least one of said hydrophobic additives <u>comprises</u> a water-insoluble polymer.
- 19. (Previously Presented) The apparatus of claim 15 wherein water-soluble constituents are bound to said at least one hydrophobic additive via a binding method selected from a group consisting of covalent binding, ion pairing, and Van der Waal's forces.
- 20. (Previously Presented) The apparatus of claim 15 wherein said at least one hydrophobic additive may react when said photoresist is used to modulate susceptibility to etch.
- 21. (Previously Presented) The apparatus of claim 14 wherein said particular liquid is comprises water and said one or more additives comprises at least one hydrophilic additive.
- 22. (Previously Presented) The apparatus of claim 21 wherein said at least one hydrophilic additive comprises a water-soluble quencher.
- 23. (Previously Presented) The apparatus of claim 21 wherein said at least one hydrophilic additive comprises a water-soluble buffer.

- 24. (Previously Presented) The apparatus of claim 21 wherein said at least one hydrophilic additive comprises a water-soluble surfactant.
- 25. (Previously Presented) The apparatus of claim 24 wherein said water-soluble surfactant comprises a fluorocarbon-based surfactant.
- 26. (Previously Presented) The apparatus of claim 21 wherein said at least one hydrophilic additive comprises a water-soluble plasticizer.
- 27. (Currently Amended) A system comprising:

a last lens element of a lithography exposure system, said last lens element having a specific index of refraction;

an index-matching liquid in contact with said last lens element, said indexmatching liquid having an index of refraction equal to said specific index of refraction to within a specified tolerance; and

a photoresist layer in contact with said index-matching liquid, said photoresist layer composed of photoresist having incorporated therein one or more constituents that improve contact liquid-contact properties between said index-matching liquid and said photoresist layer.

- 28. (Previously Presented) The system of claim 27 wherein said index-matching liquid comprises water and said one or more constituents comprises at least one waterinsoluble constituent.
- 29. (Previously Presented) The system of claim 28 wherein said at least one water-insoluble constituent comprises a constituent selected from a group consisting of a non-ionic photoacid generator, a hydrophobic ionic photoacid generator, a quencher, a polymer, an oligomer, and a molecular species.
- 30. (Previously Presented) The system of claim 27 wherein said index-matching liquid comprises water and said one or more constituents comprises at least one water-soluble constituent wherein said at least one water-soluble constituents comprises a constituent selected from a group consisting of a water-soluble photoacid generator, a water-soluble quencher, a water-soluble buffer, a water-soluble surfactant, and a water-soluble plasticizer.